
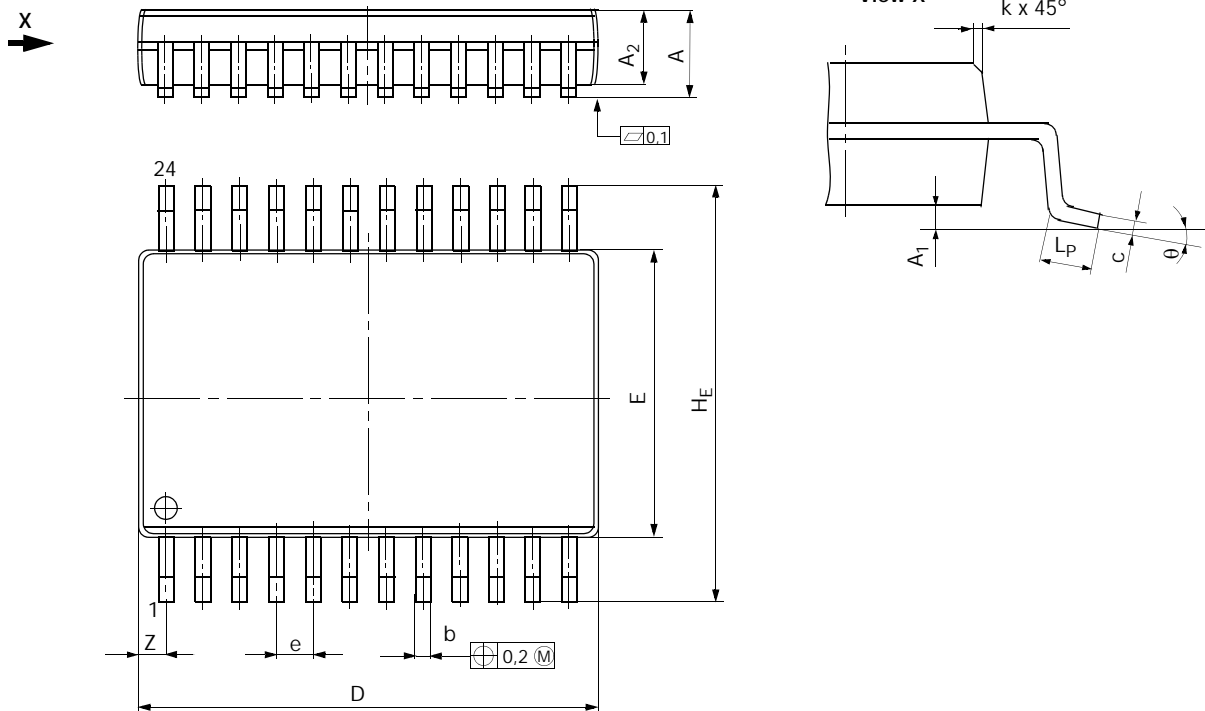


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|---|-----------------------------------|--------------------------|
|  | Package SOP24 (300 mil) | MDS 739 |
|---|-----------------------------------|--------------------------|

Maße in mm

Supersedes

Based on IEC 191-2Q: Type 075E05 B

1 Dimensions

| Dimensions of Sub-Group B1 | |
|----------------------------|-------|
| A_{max} | 2,65 |
| b_{Pmin} | 0,35 |
| b_{Pmax} | 0,49 |
| e_{nom} | 1,27 |
| H_{Emin} | 10,00 |
| H_{Emax} | 10,65 |
| L_{Pmin} | 0,40 |
| Z_{max} | 0,82 |

| Dimensions of Sub-Group C1 | |
|----------------------------|-------|
| A_{min} | 2,45 |
| A_{1min} | 0,10 |
| A_{1max} | 0,30 |
| A_{2min} | 2,25 |
| A_{2max} | 2,45 |
| c_{min} | 0,23 |
| c_{max} | 0,32 |
| D_{min}^* | 15,20 |
| D_{max}^* | 15,60 |
| E_{min}^* | 7,40 |
| E_{max}^* | 7,60 |
| k_{min} | 0,25 |
| θ_{min} | 0° |
| θ_{max} | 8° |

- 2 Weight** $\leq 0,7$ g
- 3 Package Body Material** Low stress epoxy
- 4 Lead Material** FeNi-Alloy or Cu-Alloy
- 5 Lead Finish** solder plating
- 6 Lead Form** Z-bends

* without mold-flash

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|--------------------------------------|------------------------|----------------------------|
| Zentrum Mikroelektronik Dresden GmbH | | |
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